

a bonding step of bonding a region of said semiconductor device to a region of said substrate by means of an adhesive;

62 a testing step of performing a test of electrical properties on said semiconductor device and said substrate that are connected to each other; and

a separating/sealing step of separating said semiconductor device from said substrate after heating a bonding place of said adhesive up to a temperature higher than a glass transition point or a melting point of said adhesive if it is determined that said electrical properties are poor in said testing step, and sealing said semiconductor device and said substrate by means of a sealing resin if it is determined that said electrical properties are good in said testing step.

7. A method of producing a mounting structure comprising:

a connecting step of flip-chip mounting a semiconductor device onto a substrate;

63 a bonding step of bonding a region of said semiconductor device to a region of said substrate by means of an adhesive;

a peeling permitting layer forming step of forming a peeling permitting layer on an adhesive abutting region of said semiconductor device and/or an adhesive abutting region of said substrate, said peeling permitting layer forming step being performed before said bonding step;

a testing step of performing a test of electrical properties on said semiconductor device and said substrate that are connected to each other; and

a separating/sealing step of separating said semiconductor device from said substrate if it is determined that said electrical properties are poor in said testing step, and

B3 sealing a gap between said semiconductor device and said substrate by means of a sealing resin if it is determined that said electrical properties are good in said testing step.

SEE APPENDIX FOR CHANGES MADE TO CLAIMS AND SPECIFICATION

Please add the following new claims:

B4 --21. A method of producing a mounting structure according to claim 1, wherein said connecting step includes electrically connecting an electrode pad of the semiconductor device to a terminal electrode of the substrate using an electrically conductive adhesive.

22. A method of producing a mounting structure according to claim 1, wherein each of said regions in said bonding step is not involved in an electrical connection.

23. A method of producing a mounting structure according to claim 7, wherein each of said regions in said bonding step is not involved in an electrical connection.

24. A method of producing a mounting structure according to claim 1, wherein said bonding step includes curing said adhesive.--